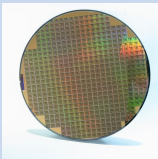

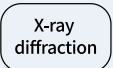

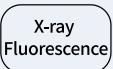





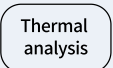

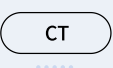

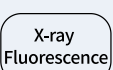



Field/Category	Technology	Product name/ Series name	Function/Role
 	 X-ray diffraction 	XRTmicron , TFXRD , SmartLab , FSAS	Use of X-ray analysis to examine the condition and quality of crystals in semiconductors enables improvement of semiconductor quality and production methods.
	 X-ray Fluorescence 	AZX 400 , WaferX 310 など	In the semiconductor manufacturing process, the quantity deposited in each layer of layer deposition must be carefully managed to obtain the desired material characteristics. Wavelength dispersive X-ray fluorescence (WDXRF) offers exceptional resolution, enabling evaluation of deposition of a wide range of semiconductor materials.
	 X-ray Fluorescence 	TXRF series	Contamination of wafers in the semiconductor manufacturing process is a factor in the reduction of yield. The Total Reflection X-Ray Fluorescence Analysis Series enables high-speed screening for contamination of wafer surfaces.
 	 Thermal analysis 	TG-DTA , DSC series , TMA	Thermal analyzers are used to evaluate the thermal characteristics (melting point, rate of expansion, glass transition) of epoxy resins, ceramics and lead-free solders used in electronic circuit boards. They provide vital feedback on selection and compounding of materials and production processes.
	 CT 	CT Lab series	When electronic products fail, the cause of the failure must be isolated, and for this the product must normally be finely taken apart and sectioned. With XCT, however, these causes can be identified in a non-destructive manner, providing valuable feedback to prevent recurrence of the failure. Growing numbers of manufacturers are incorporating XCT into manufacturing processes for pass/failure judgment of products.
	 X-ray Fluorescence 	ZSX Primus series , Supermini200 , EDX series	The use of hazardous substances such as lead and mercury in electronic devices is subject to restrictions, requiring confirmation through receiving inspection at production sites. X-ray fluorescence spectrometry enables these hazardous substances to be detected easily and non-destructively.